



# PMEG2005CT

20 V, 500 mA low VF dual Schottky barrier rectifier

8 October 2024

Product data sheet

## 1. General description

Planar Schottky barrier rectifier in common cathode configuration with an integrated guard ring for stress protection, encapsulated in a SOT23 small Surface-Mounted Device (SMD) plastic package.

## 2. Features and benefits

- Average forward current:  $I_{F(AV)} \leq 0.5$  A
- Reverse voltage:  $V_R \leq 20$  V
- Small SMD plastic package
- Low forward voltage

## 3. Applications

- Low voltage rectification
- Reverse polarity protection
- High efficiency DC-to-DC conversion
- High-speed switching
- Switch Mode Power Supply (SMPS)
- Low power consumption applications

## 4. Quick reference data

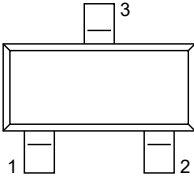
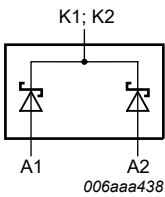
Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Per diode							
$V_R$	reverse voltage	$T_j = 25$ °C		-	-	20	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; $f = 20$ kHz; square wave; $T_{amb} \leq 100$ °C	[1]	-	-	0.5	A
		$\delta = 0.5$ ; $f = 20$ kHz; square wave; $T_{sp} \leq 130$ °C		-	-	0.5	A
$V_F$	forward voltage	$I_F = 0.5$ A; $T_j = 25$ °C		-	360	390	mV
$I_R$	reverse current	$V_R = 20$ V; $T_j = 25$ °C		-	30	200	µA

[1] Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint.

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A	anode (diode 1)	 SOT23	 006aaa438
2	A	anode (diode 2)		
3	K1, K2	common cathode (diode 1 and diode 2)		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
<a href="#">PMEG2005CT</a>	SOT23	plastic, surface-mounted package; 3 terminals; 1.9 mm pitch; 2.9 mm x 1.3 mm x 1 mm body	<a href="#">SOT23</a>

7. Marking

Table 4. Marking codes

Type number	Marking code[1]
PMEG2005CT	P8%

[1] % = placeholder for manufacturing site code

8. Limiting values

Table 5. Limiting values  
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
Per diode						
V <sub>R</sub>	reverse voltage	T <sub>j</sub> = 25 °C		-	20	V
I <sub>F(AV)</sub>	average forward current	δ = 0.5; f = 20 kHz; square wave; T <sub>amb</sub> ≤ 100 °C	[1]	-	0.5	A
		δ = 0.5; f = 20 kHz; square wave; T <sub>sp</sub> ≤ 130 °C		-	0.5	A
I <sub>FRM</sub>	repetitive peak forward current	t <sub>p</sub> ≤ 1 ms; δ ≤ 0.25		-	3.9	A
I <sub>FSM</sub>	non-repetitive peak forward current	t <sub>p</sub> = 8 μs; square wave; T <sub>j(init)</sub> = 25 °C		-	10	A
Per device; one diode loaded						
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C	[2]	-	330	mW
			[3]	-	400	mW
			[1]	-	460	mW
T <sub>j</sub>	junction temperature			-	150	°C
T <sub>amb</sub>	ambient temperature			-55	150	°C
T <sub>stg</sub>	storage temperature			-65	150	°C

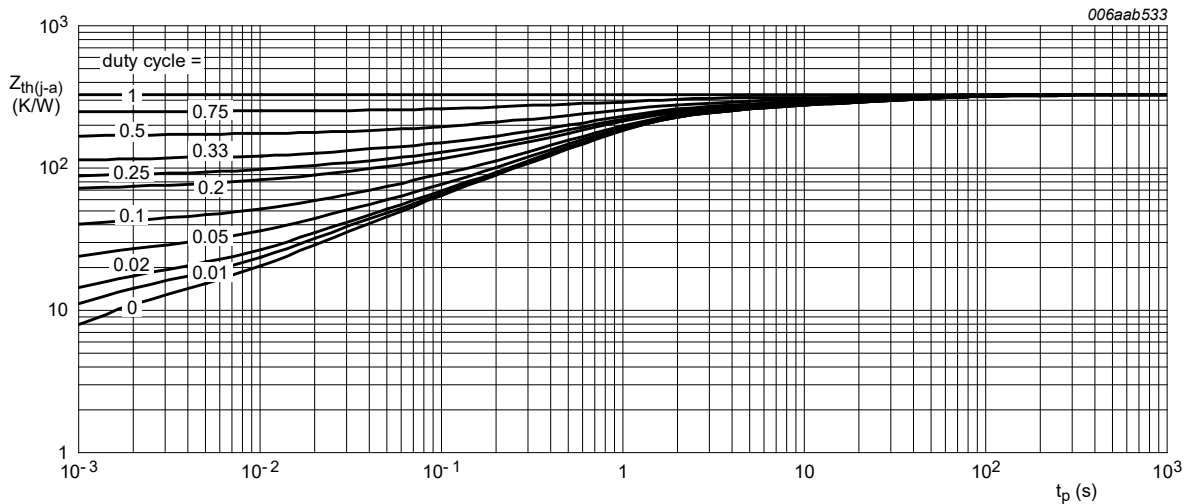
- [1] Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint.  
[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.  
[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1cm<sup>2</sup>.

9. Thermal characteristics

Table 6. Thermal characteristics

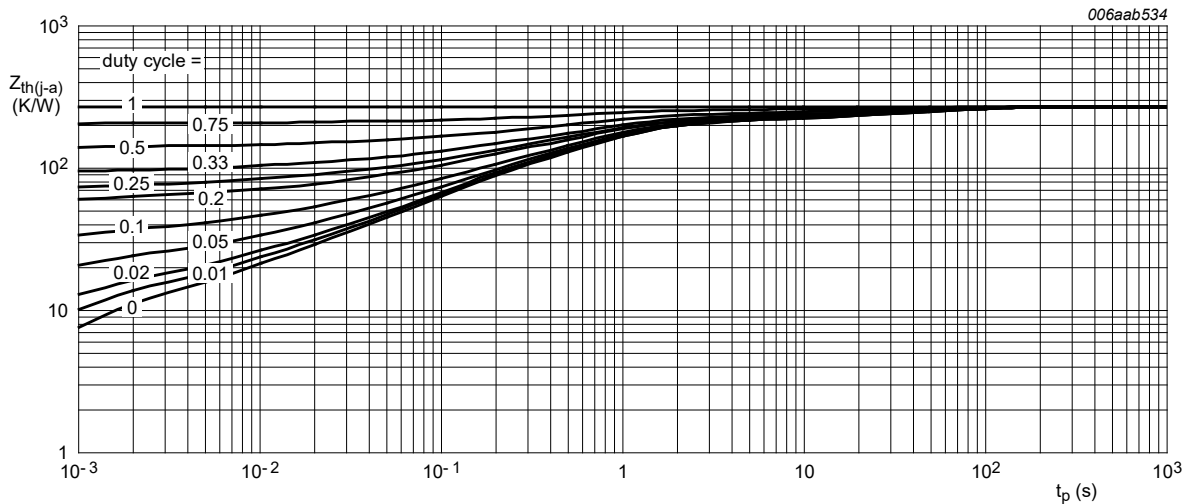
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Per device; one diode loaded							
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	in free air	[1] [2]	-	-	375	K/W
			[1] [3]	-	-	310	K/W
			[1] [4]	-	-	270	K/W
R <sub>th(j-sp)</sub>	thermal resistance from junction to solder point		[5]	-	-	60	K/W

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P<sub>R</sub> are a significant part of the total power losses.  
[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.  
[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.  
[4] Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint.  
[5] Soldering point of cathode tab.



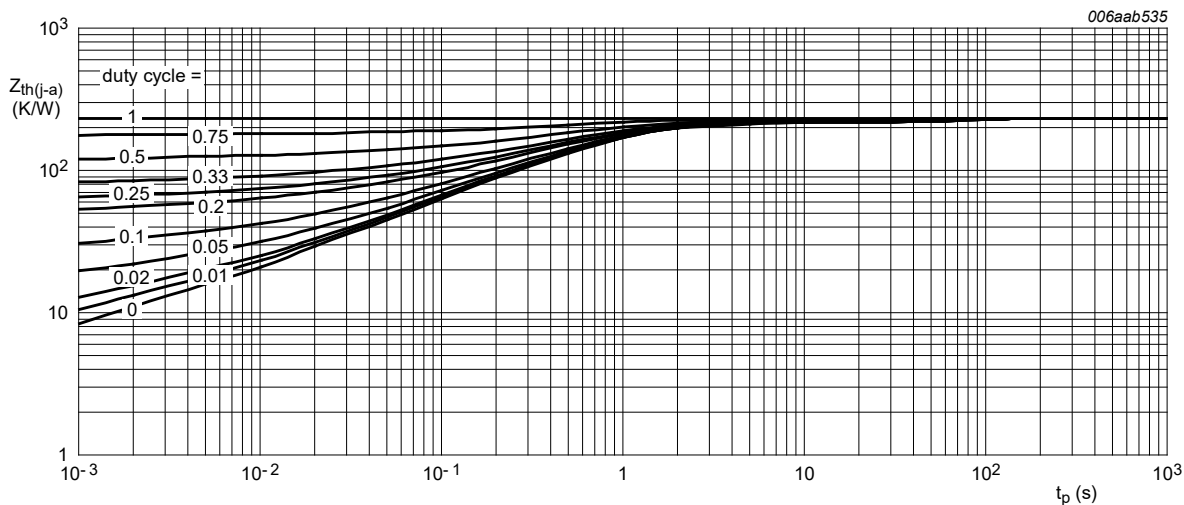
FR4 PCB, standard footprint

Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>

Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



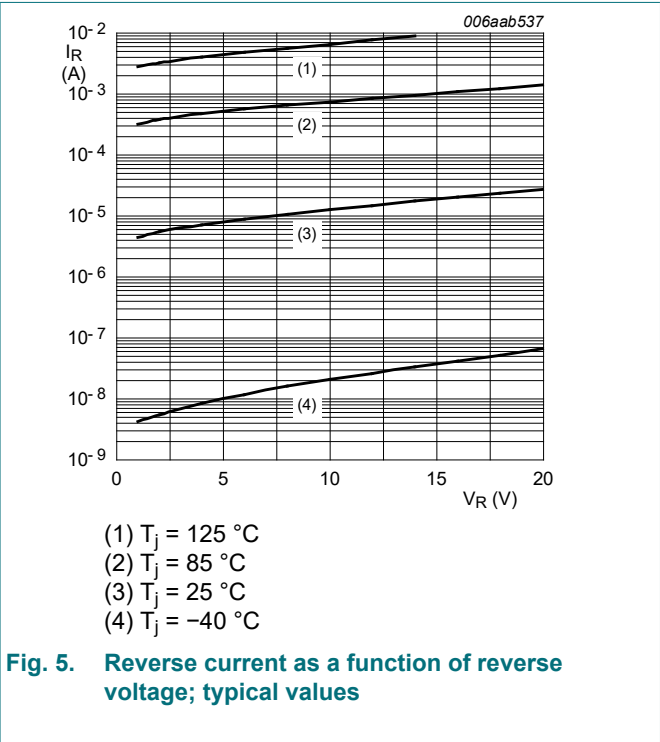
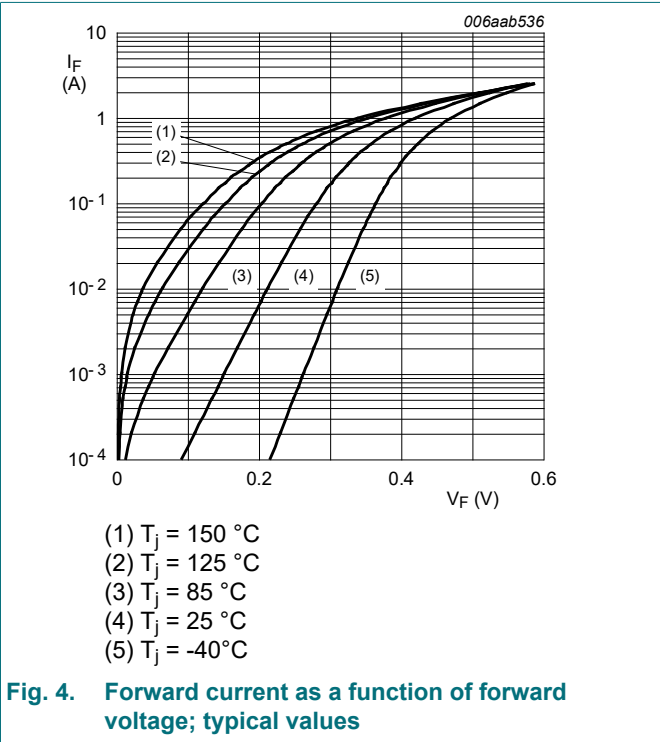
Ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint

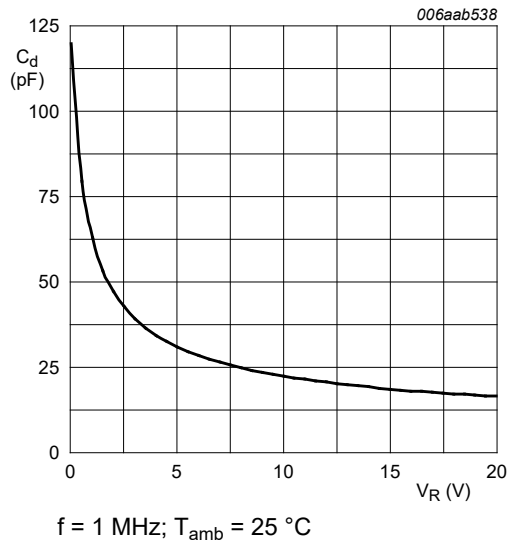
Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

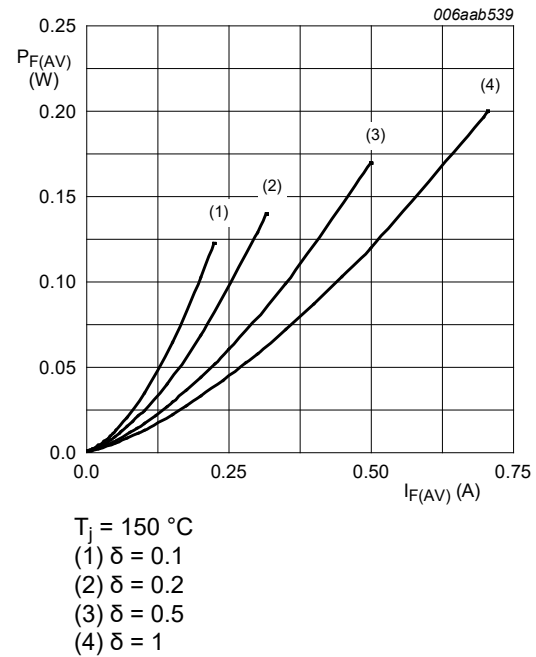
Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Per diode							
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 0.1 mA; T <sub>j</sub> = 25 °C		-	95	130	mV
		I <sub>F</sub> = 1 mA; T <sub>j</sub> = 25 °C		-	155	190	mV
		I <sub>F</sub> = 10 mA; T <sub>j</sub> = 25 °C		-	215	240	mV
		I <sub>F</sub> = 100 mA; T <sub>j</sub> = 25 °C		-	285	330	mV
		I <sub>F</sub> = 0.5 A; T <sub>j</sub> = 25 °C		-	360	390	mV
I <sub>R</sub>	reverse current	V <sub>R</sub> = 10 V; T <sub>j</sub> = 25 °C		-	11	40	µA
		V <sub>R</sub> = 20 V; T <sub>j</sub> = 25 °C		-	30	200	µA
C <sub>d</sub>	diode capacitance	V <sub>R</sub> = 1 V; f = 1 MHz; T <sub>j</sub> = 25 °C		-	66	80	pF
t <sub>rr</sub>	reverse recovery time	When switched from I <sub>F</sub> = 10 mA to I <sub>R</sub> = 10 mA; R <sub>L</sub> = 100 Ω; measured at I <sub>R</sub> = 1 mA.		-	22	-	ns

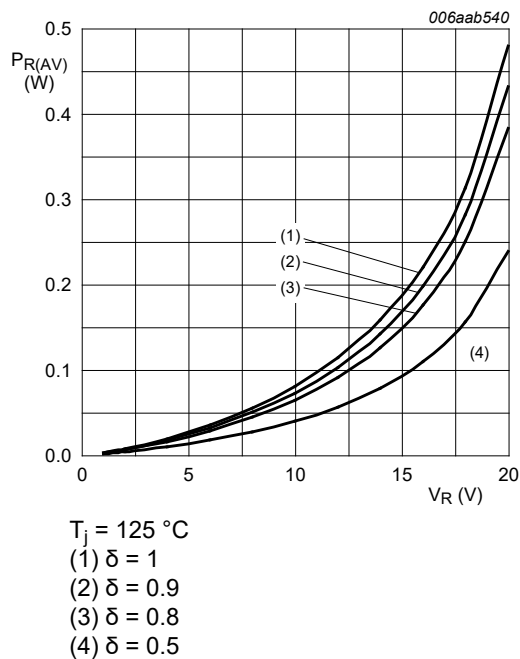




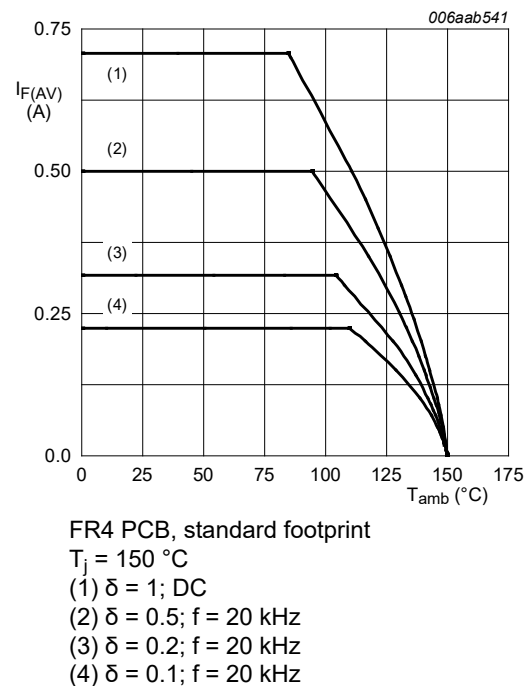
**Fig. 6.** Diode capacitance as a function of reverse voltage; typical values



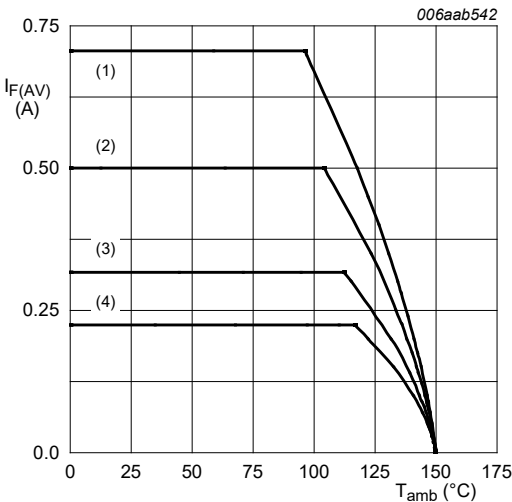
**Fig. 7.** Average forward power dissipation as a function of average forward current; typical values



**Fig. 8.** Average reverse power dissipation as a function of reverse voltage; typical values

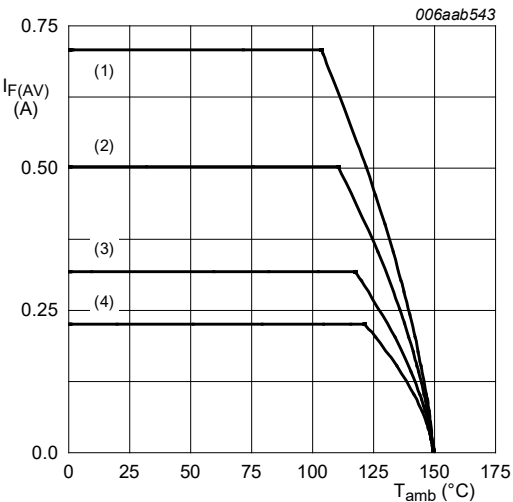


**Fig. 9.** Average forward current as a function of ambient temperature; typical values



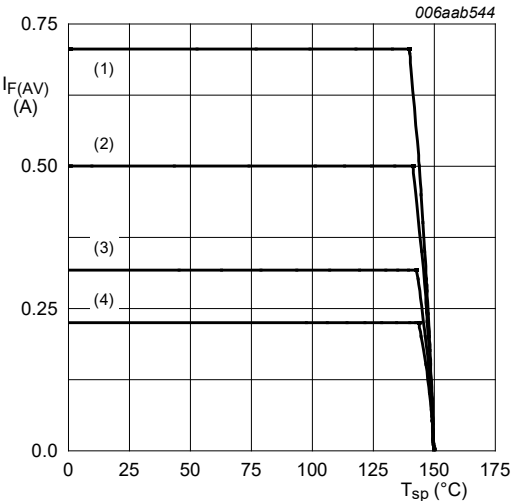
FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>  
 $T_j = 150$  °C  
(1)  $\delta = 1$ ; DC  
(2)  $\delta = 0.5$ ;  $f = 20$  kHz  
(3)  $\delta = 0.2$ ;  $f = 20$  kHz  
(4)  $\delta = 0.1$ ;  $f = 20$  kHz

Fig. 10. Average forward current as a function of ambient temperature; typical values



Ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint  
 $T_j = 150$  °C  
(1)  $\delta = 1$ ; DC  
(2)  $\delta = 0.5$ ;  $f = 20$  kHz  
(3)  $\delta = 0.2$ ;  $f = 20$  kHz  
(4)  $\delta = 0.1$ ;  $f = 20$  kHz

Fig. 11. Average forward current as a function of ambient temperature; typical values



$T_j = 150$  °C  
(1)  $\delta = 1$ ; DC  
(2)  $\delta = 0.5$ ;  $f = 20$  kHz  
(3)  $\delta = 0.2$ ;  $f = 20$  kHz  
(4)  $\delta = 0.1$ ;  $f = 20$  kHz

Fig. 12. Average forward current as a function of solder point temperature; typical values

11. Test information

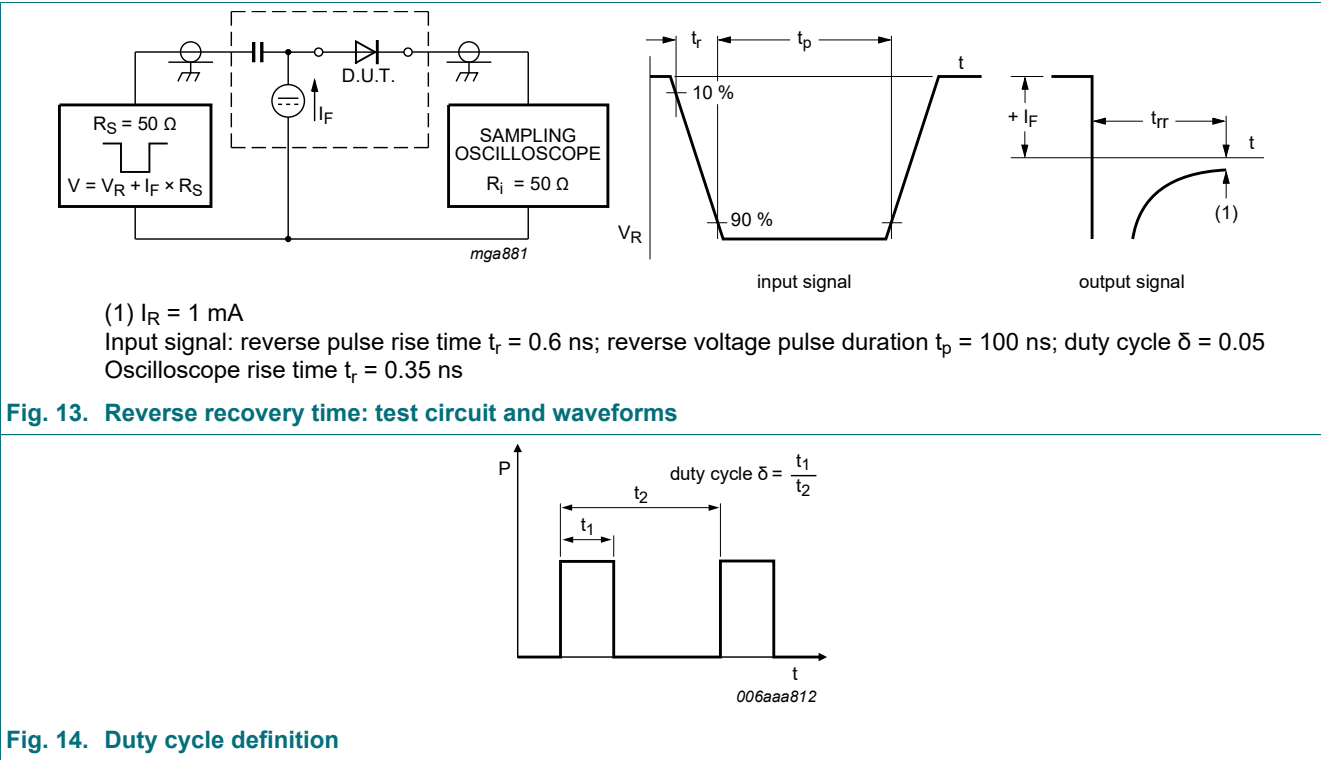
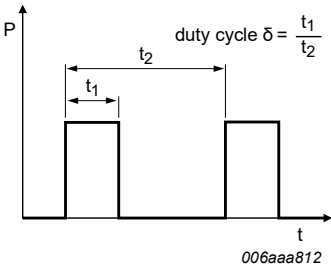


Fig. 14. Duty cycle definition



The current ratings for the typical waveforms are calculated according to the equations:

$I_{F(AV)} = I_M \times \delta$  with  $I_M$  defined as peak current

$I_{RMS} = I_{F(AV)}$  at DC

$I_{RMS} = I_M \times \sqrt{\delta}$  with  $I_{RMS}$  defined as RMS current

12. Package outline

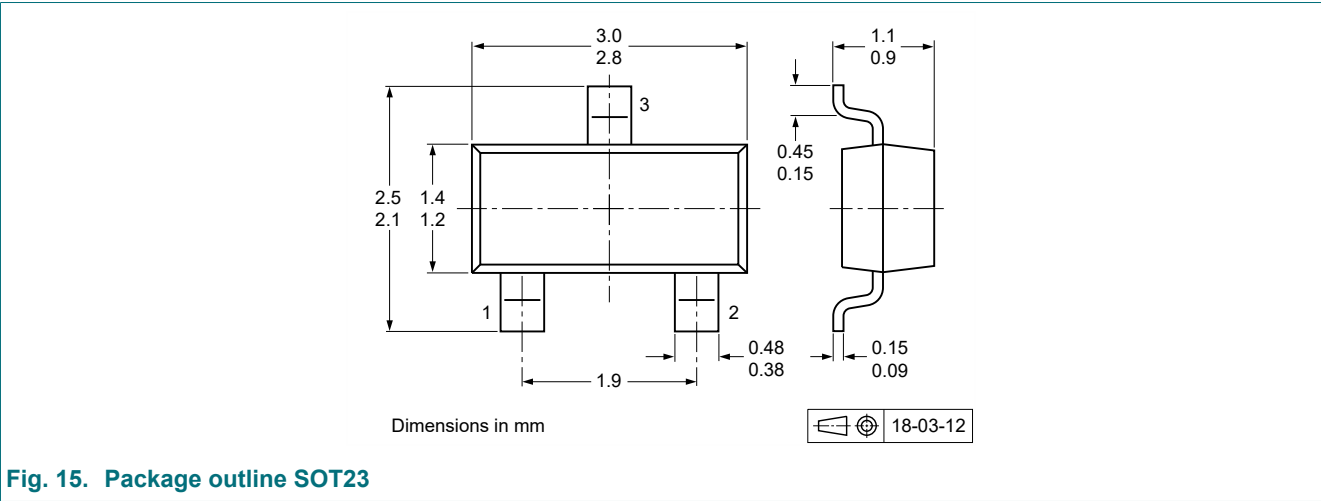


Fig. 15. Package outline SOT23



13. Soldering



Fig. 16. Reflow soldering footprint for SOT23

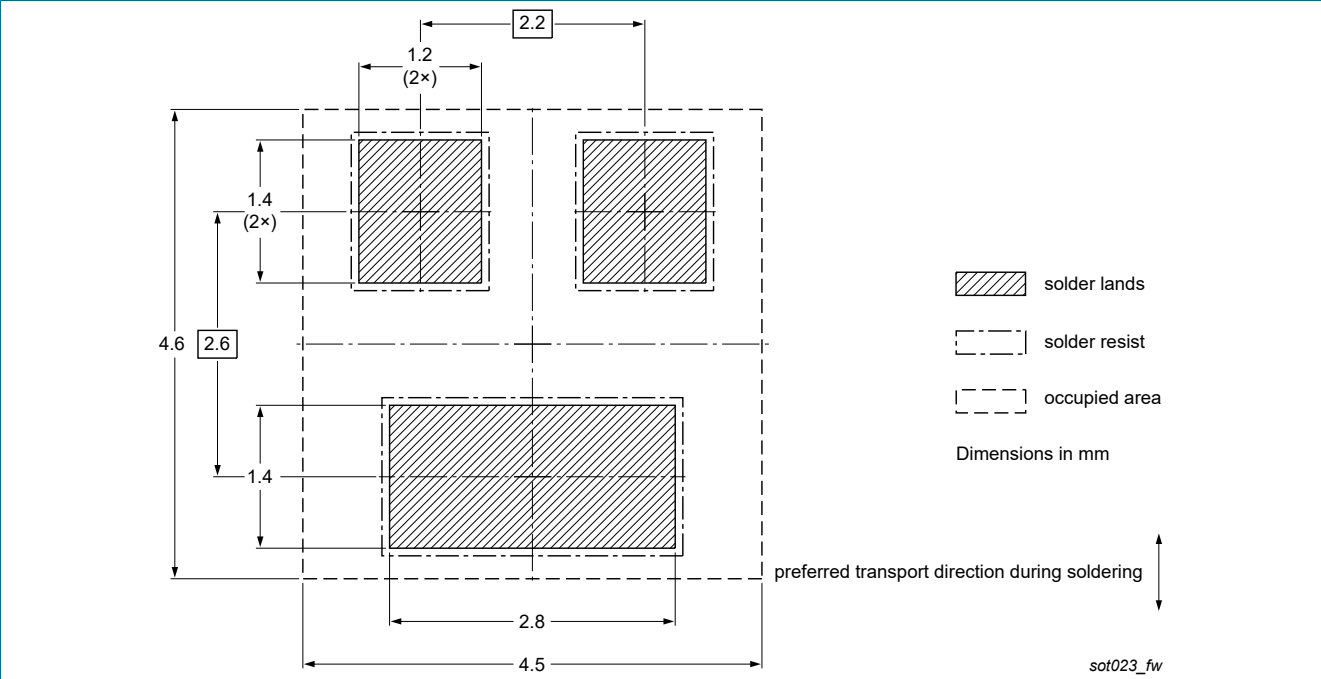


Fig. 17. Wave soldering footprint for SOT23

14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG2005CT v.4	20241008	Product data sheet	-	PMEG2005CT v.3
Modifications:	<ul style="list-style-type: none"><li>Product(s) changed to non-automotive qualification. Please refer to nexperia.com for automotive (-Q) product alternative(s).</li></ul>			
PMEG2005CT v.3	20230626	Product data sheet	-	PMEG2005CT v.2
PMEG2005CT v.2	20100622	Product data sheet	-	PMEG2005CT_1
PMEG2005CT_1	20090604	Product data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the internet at <https://www.nexperia.com>.

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